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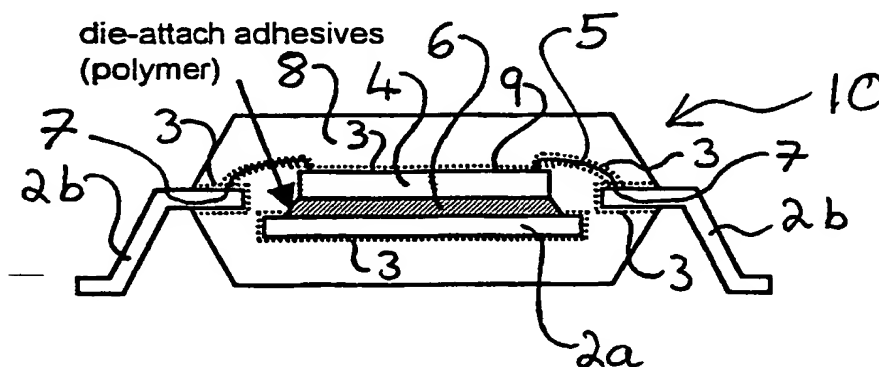
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(54) Title: A METHOD OF ASSEMBLING A SEMICONDUCTOR DEVICE PACKAGE



(57) **Abstract:** A method of assembling a semiconductor device package (10) includes first attaching a semiconductor device (4) to a die-pad area (2a) of a leadframe (2). Electrical connections (5) are then formed between electrical contact areas on the semiconductor device (4) and electrical contact areas (7) on the leadframe (2) to form a device/leadframe assembly (2, 4, 5). An adhesion enhancing coating (3) is then deposited on exposed surfaces of the device/leadframe assembly (2, 4, 5) before encapsulating the coated device/leadframe assembly (2, 4, 5) in an electrically insulating material.

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